



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20240826003.1

**Qualification of RFAB using qualified Process Technology, Die Revision, Datasheet update and additional Assembly BOM options for select devices
Change Notification / Sample Request**

Date: August 26, 2024

To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments (TI). The details of this change are on the following pages, and are in alignment with our standard product change notification (PCN) [process](#).

TI requires acknowledgement of receipt of this notification within 30 days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 30 days of this notification, given that samples are not built ahead of the change.

The Proposed First Ship date in this PCN letter is the earliest possible date that customers could receive the changed material. It is our commitment that the changed device will not ship before that date. If samples are requested within the 30 day sample request window, customers will still have 30-days to complete their evaluation regardless of the proposed 1st ship date.

This particular PCN is related to TI's multiyear transition plan for our two remaining factories with 150-millimeter production (DFAB in Dallas, Texas, and SFAB in Sherman, Texas). DFAB will remain open, but will focus on 200-mm production, with a smaller set of technologies. SFAB will close no earlier than 2024 and no later than 2025. As referenced in the "reason for change" below, these changes are part of our multiyear plan to transition these products to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the Change Management team. For sample requests or sample related questions, contact your local Field Sales Representative. As always, we thank you for your continued business.

Change Management Team
SC Business Services

20240826003.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
GD75232DBR	NULL
GD75232PWR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20240826003.1	PCN Date:	August 26, 2024
Title:	Qualification of RFAB using qualified Process Technology, Die Revision, Datasheet update and additional Assembly BOM options for select devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	November 24, 2024	Sample requests accepted until:	September 25, 2024*

***Sample requests received after September 25, 2024 will not be supported.**

Change Type:					
<input type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Wafer Fab Material
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input checked="" type="checkbox"/>	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional Wafer Fab option in addition to Assembly BOM options for the devices listed below.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
SFAB	J11	150 mm	RFAB	T1B	300 mm

The die was also changed as a result of the process change.

Construction differences are as follows:

	Current	Proposed
Wire diam/type	0.96 mil Cu	0.80 mil Cu

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.



GD65232, GD75232

SLLS206L – MAY 2005 – REVISED AUGUST 2024

Changes from Revision K (August 2012) to Revision L (August 2024)	Page
• Changed the numbering format for tables, figures, and cross-references throughout the document.....	1
• Added the <i>Thermal Information</i> table.....	5

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
GD65232	SLLS206J	SLLS206L	http://www.ti.com/product/GD65232

Qual details are provided in the Qual Data Section.

Reason for Change:

These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
SH-BIP-1	SHE	USA	Sherman
RFAB	RFB	USA	Richardson

Die Rev:

Current

New

Die Rev [2P]	Die Rev [2P]
A, H	-

Sample product shipping label (not actual product label):



Product Affected:

GD65232PWR	GD75232DBR	GD75232PWR
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For alternate parts with similar or improved performance, please visit the product page on [TI.com](https://www.ti.com)

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: GD65232PWR	Qual Device: GD75232PWR	Qual Device: GD75232DBR	QBS Reference: LM2902BQPWRQ1	QBS Reference: SN74LVC8T245DBR	QBS Reference: TPS2074DB	QBS Reference: TLC6946DBQR	QBS Reference: MC33063AQDRQ1	QBS Reference: TMUX1134PWR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	1/77/0	-	1/77/0	3/231/0	1/77/0	-	3/231/0	3/231/0	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	1/77/0	-	-	-	-
UHAST	A3	Unbiased HAST	110C/85%RH	264 Hours	-	-	-	3/231/0	-	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	1/77/0	-	1/77/0	-	-	3/231/0	3/231/0	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	-	1/77/0	3/231/0	1/77/0	3/231/0	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	1/77/0	-	1/77/0	3/231/0	-	3/231/0	3/231/0	3/135/0	3/231/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	-	1/77/0	-	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	-	-	3/231/0	3/231/0	3/231/0
HTOL	B1	Life Test	150C	408 Hours	-	-	-	3/231/0	-	-	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	3/2400/0	-	-	-	3/2400/0	3/2400/0
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	-	-	1/15/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	-	-	1/15/0	-

Type	#	Test Name	Condition	Duration	Qual Device: GD65232PWR	Qual Device: GD75232PWR	Qual Device: GD75232DBR	QBS Reference: LM2902BQPWRQ1	QBS Reference: SN74LVC8T245DBR	QBS Reference: TPS2074DB	QBS Reference: TLC6946DBQR	QBS Reference: MC33063AQDRQ1	QBS Reference: TMUX1134PWR
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	-	-	-	-	-	-	1/22/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	3/30/0	-	-	-	3/30/0	-
ESD	E2	ESD CDM	-	1500 Volts	-	-	-	3/9/0	-	-	-	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	1/3/0	-	1/3/0	-	1/3/0	-	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	-	-	-	1/3/0	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	-	1/3/0	-	1/3/0	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	3/9/0	-	-	-	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	3/18/0	1/3/0	-	1/3/0	1/6/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	1/30/0	-	3/90/0	-	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	3/90/0	-	-	-	3/90/0	-

- QBS: Qual By Similarity
- Qual Device GD65232PWR is qualified at MSL1 260C
- Qual Device GD75232PWR is qualified at MSL1 260C
- Qual Device GD75232DBR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2308-117

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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